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Application ID: 10665651 *10665651*
Title of Invention: THIN AND HEAT RADIANT
SEMICONDUCTOR PACKAGE AND
METHOD FOR MANUFACTURING
First Named Inventor: Jae Ku
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TRANSMITTAL

Electronic Version v1.1
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Title of Invention	THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING	
<p>Application Number: 10/665651 *10/665651*</p> <p>Date: 2003-09-19</p> <p>First Named Applicant: Jae Hun Ku</p> <p>Confirmation Number: 6079</p> <p>Attorney Docket Number: AMKOR041G</p>		
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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney

Documents being submitted us-ids	Files ids-usidst.xml us-ids.dtd us-ids.xsl
Comments	

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING
Application Number:	10/665651 *10/665651*
Confirmation Number:	6079
First Named Applicant:	Jae Ku
Attorney Docket Number:	AMKOR041G
Art Unit:	2811
Search string:	(2596993 or 3435815 or 3734660 or 3838984 or 4054238 or 4189342 or 4258381 or 4289922 or 4301464 or 4332537 or 4417266 or 4451224 or 4530152 or 4541003 or 4646710 or 4707724 or 4727633 or 4737839 or 4756080 or 4812896 or 4862245 or 4862246 or 4907067 or 4920074 or 4935803 or 4942454 or 4987475 or 5018003 or 5029386 or 5041902 or 5057900 or 5059379 or 5065223 or 5070039 or 5087961 or 5091341 or 5096852 or 5118298 or 5151039 or 5157475 or 5157480 or 5168368 or 5172213 or 5172214 or 5175060 or 5200362 or 5200809 or 5214845 or 5216278 or 5218231 or 20010008305 or 20010014538 or 20010011654 or 20020024122 or 20020027297 or 20020140061 or 20020140068 or 20020163015 or 20030030131 or 20030073265).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
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Signature

Examiner Name	Date